

IKA standard distribution board, IP65 without clamps

Powering Business Worldwide*

Part no. IKA-3/36-0T Article no. 174208 Catalog No. IKA-3/36-0T

Delivery program

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Basic function		Basic device
Product function		Installation distribution boards
Product range		IKA standard DBO
Design		Surface mounted
Installation site		Indoor
Type of installation		Surface mounting
Door/Flap		Transparent
Degree of Protection		IP65
Colour		Grey
Module rack		Rail-frame
Shroud for protection against accidental contact		Plastic
Rows	Count	3
Module units per row		12
Description		IP65 Protection Class II Plastic enclosure gray (RAL 7035)
Cable entries		Metric cable entries on top and bottom, side, back plate
PE and N terminals design		Without
Equipment supplied		Basic device Device support rails Locking screws can be sealed Sealing caps Current circuit designation

Technical data

General

Standards			EN 62208, IEC/EN 60670-24
RoHS (in accordance with Directive 2002/95/EC of the European Parliament and Council)			conform
Ambient temperature		°C	-25 - +40
Degree of Protection			IP65
Protection class			II (totally insulated)
Rated operational voltage	Ue	V AC	415
Rated frequency	f	Hz	50
Material characteristics			
Material			ABS (plastic)
Colour			Gray (RAL 7035)
Motorial proportios			

Material properties

Mechanical	
Impact resistance	IK08

Design verification as per IEC/EN 61439

Technical data for design verification			
Heat dissipation, at an ambient temperature of 35°C, delta T: 20 degrees, calculated as per IEC 60890 $$			
Individual enclosure for wall mounting	P_{V}	CO	37
Heat dissipation, at an ambient temperature of 35°C, delta T: 35 degrees, calculated as per IEC 60890			
Individual enclosure for wall mounting	P_{V}	CO	75

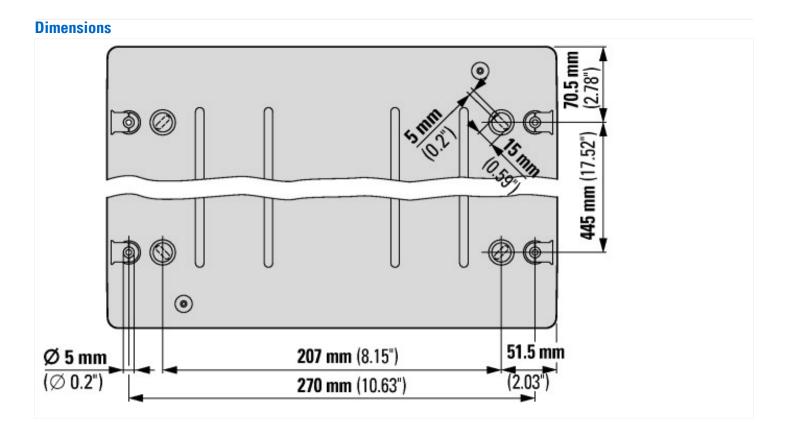
10.2 Strength of materials and parts 10.2.2 Corrosion resistance 10.2.3.1 Verification of thermal stability of enclosures 10.2.3.2 Verification of resistance of insulating materials to normal heat 10.2.3.3 Verification of resistance of insulating materials to normal heat 10.2.3.3 Verification of resistance of insulating materials to abnormal heat and fire due to internal electric effects 10.2.4 Resistance to ultra-violet (UV) radiation 10.2.5 Lifting 10.2.6 Mechanical impact 10.2.6 Mechanical impact 10.2.7 Inscriptions 10.3.0 Egree of protection of ASSEMBLIES 10.4 Clearances and creepage distances 10.5 Protection against electric shock 10.6 Incorporation of switching devices and components 10.7 Internal electrical circuits and connections 10.8 Incorporation of switching devices and components 10.9 Insulation properties 10.9 Insulation prop	IEC/EN 61439 design verification	
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10.13 Mechanical function Meets the product standard's requirements.	10.12 Electromagnetic compatibility	Is the panel builder's responsibility.
	10.13 Mechanical function	Meets the product standard's requirements.

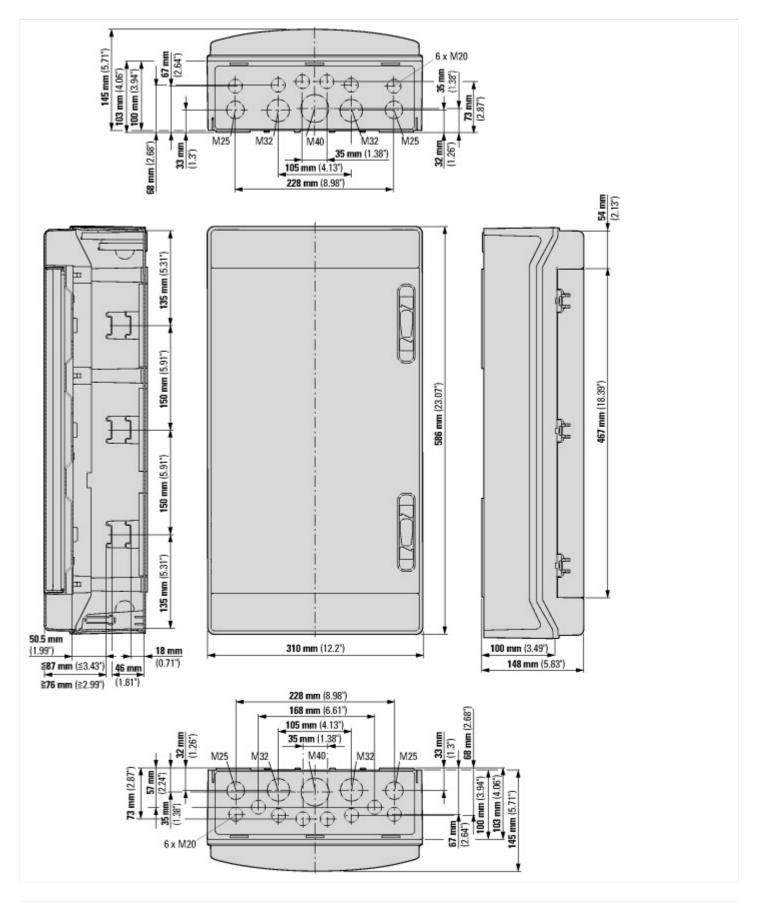
Technical data ETIM 6.0

Distribution boards (EG000023) / Small distribution board (EC000214)

Electric engineering, automation, process control engineering / Electrical installation, device / Electrical distribution system (incl. small distribution board) / Small distribution board (ecl@ss8.1-27-14-24-09 [ACN387008])

Mounting method		Surface mounting
Number of rows		3
Width in number of modular spacings		12
Type of cover		Door
Cover model .		With notch
Transparent cover/door		Yes
Material housing		Plastic
Height	mm	586
Width	mm	310
Depth	mm	145
Built-in depth	mm	70
Internal depth	mm	60
DIN-rail		Yes
With mounting plate		No
Extension possible		Yes
EMC-version		No
Colour		Grey
RAL-number		7035
Degree of protection (IP)		IP65
With lock		No





Additional product information (links)

IL014003Z IKA compact distribution board	
IL014003Z IKA compact distribution board	ftp://ftp.moeller.net/DOCUMENTATION/AWA_INSTRUCTIONS/IL014003ZU2015_03.pdf
Product overview (Web)	http://www.eaton.eu/DE/Europe/Electrical/ProductsServices/Residential/index.htm